



Organizational Chart

Europe

Japan

North America | China | Korea | Taiwan

June 2026 v2

STANDARDS

Outline

- 1** Global Technical Committee and Technical Committee Chapters
- 2** Regional Standards Committee Organizations
- 3** Organization of Each TC Chapter

GTC and TC Chapters

GTC = Global Technical Committee

TC = Technical Committee

Global Technical Committee	Locale					
	China	<u>Europe</u>	<u>Japan</u>	Korea	<u>North America</u>	Taiwan
3D Packaging & Integration*			TCC		TCC	TCC
Automated Test Equipment					TCC	
Automation Technology			TCC			TCC
Compound Semiconductor Materials	TCC	TCC	TCC		TCC	
HB-LED	TCC				TCC	
EH&S			TCC	TCC	TCC	TCC
Information & Control	TCC		TCC	TCC	TCC	TCC

Legend:

TCC – The Locale has a TC Chapter of the global technical committee.

CFG – The Locale has a TC Chapter Formation Group, as defined in PM 6.5, of the global technical committee.

Note 1: An underlined Locale has an RSC and may also be referred as “a Region” (e.g., Europe Region)

Note 2: Some TC Chapters of different global technical committees jointly hold a meeting (indicated in purple rectangles)

*3DS-IC GTC and Assembly & Packaging GTC were integrated into one new GTC as 3D Packaging & Integration GTC in July 2017.

Global Technical Committee \ Locale	China	<u>Europe</u>	<u>Japan</u>	Korea	<u>North America</u>	Taiwan
Facilities			TCC	TCC	TCC	
Gases		TCC	TCC		TCC	
Liquid Chemicals		TCC	TCC		TCC	
FPD Materials & Components			TCC			
FPD Metrology				TCC		TCC
Flexible Hybrid Electronics			TCC		TCC	TCC
MEMS/NEMS					TCC	

Legend:

TCC – The Locale has a TC Chapter of the global technical committee.

CFG – The Locale has a TC Chapter Formation Group, as defined in PM 6.5, of the global technical committee.

Note 1: An underlined Locale has an RSC and may also be referred as “a Region” (e.g., Europe Region)

Note 2: Some TC Chapters of different global technical committees jointly hold a meeting (indicated in purple rectangles)

Global Technical Committee	Locale	China	<u>Europe</u>	<u>Japan</u>	Korea	<u>North America</u>	Taiwan
	Metrics				TCC		TCC
Micropatterning (Microlithography*)						TCC	
Photovoltaic (PV)		TCC				TCC	TCC
PV Materials		TCC				TCC	
Physical Interfaces & Carriers				TCC		TCC	
Silicon Wafer			TCC	TCC		TCC	
Traceability				TCC		TCC	

Legend:

TCC – The Locale has a TC Chapter of the global technical committee.

CFG – The Locale has a TC Chapter Formation Group, as defined in PM 6.5, of the global technical committee.

Note 1: An underlined Locale has an RSC and may also be referred as “a Region” (e.g., Europe Region)

Note 2: Some TC Chapters of different global technical committees jointly hold a meeting (indicated in purple rectangles)

*In NA, Micropatterning is traditionally called Microlithography.

RSC Organizations

RSC = Regional Standards Committee

SEMI Europe RSC Organization

**Europe Chapter of Liquid Chemicals
Global Technical Committee**

C: Jochen Ruth – Pall Corporation

**Europe Chapter of
Compound Semiconductor Materials
Global Technical Committee**

C: Arnd Weber – SiCrystal
C: Christian Kranert – Fraunhofer IISB

**Europe Chapter of Gases
Global Technical Committee**

C: Jochen Ruth – Pall Corporation

**Europe Chapter of Silicon Wafer
Global Technical Committee**

C: Werner Bergholz – International Standards Consulting
C: Fritz Passek – Siltronic
C: Frank Riedel – Siltronic

SEMI Japan RSC Organization

**Japan Chapter of
3D Packaging & Integration
Global Technical Committee**
C: Masahiro Tsuruya – iNEMI
C: Haruo Shimamoto – AIST

**Japan Chapter of
Automation Technology
Global Technical Committee**
C: Terry Asakawa – Vistaideal Consulting
C: Fumiyasu Obuchi – SIEMENS
C: Yasuhiro Kaneko – YAMAHA Motor

**Japan Chapter of
Compound Semiconductor Materials
Global Technical Committee**
C: Masayoshi Obara – Shin-Etsu Handotai
C: Makoto Kitabatake – Self

**Japan Chapter of
Environmental Health & Safety
Global Technical Committee**
C: Supika Mashiro – Tokyo Electron Limited
C: Moray Crawford – Hatsuta Seisakusho

**Japan Chapter of Facilities
Global Technical Committee**
C: Hiromichi Enami – i ZOOM
C: Isao Suzuki – Consultant
C: Masafumi Kitano – Fujikin

**Japan Chapter of
Flexible Hybrid Electronics
Global Technical Committee**
C: Satoshi Maeda – Hiroshima City University
C: Manabu Ito – TOPPAN Holdings
C: Tadahiro Furukawa – Yamagata University

**Japan Chapter of
FPD Materials & Components
Global Technical Committee**
C: Tadahiro Furukawa – Yamagata University
C: Keitaro Kondo – HOYA
C: Toshimasa Eguchi – Sumitomo Bakelite

**Japan Chapter of Gases
Global Technical Committee**
C: Hiromichi Enami – Consultant
C: Isao Suzuki – Consultant
C: Masafumi Kitano – Fujikin

**Japan Chapter of
Information & Control
Global Technical Committee**
C: Takayuki Nishimura – SCREEN
Semiconductor Solutions
C: Mitsuhiro Matsuda – KOKUSAI ELECTRIC
C: Yuko Toyoshima – Hitachi High-Tech

**Japan Chapter of Liquid Chemicals
Global Technical Committee**
C: Yoshiyuki Fujitani – SCREEN
Semiconductor Solutions
C: Takuya Nagafuchi – Nihon Entegris

**Japan Chapter of Metrics
Global Technical Committee**
C: Mitsune Sakamoto – ZAMA Consulting

**Japan Chapter of
Physical Interfaces & Carriers
Global Technical Committee**
C: Tsuyoshi Nagashima – Mirai
C: Daisuke Sado – Eagle Industry
C: Yasuhisa Ito – Murata Machinery

**Japan Chapter of Silicon Wafer
Global Technical Committee**
C: Satoshi Akiyama – Nanoverse
Technologies
C: Ryuji Takeda – GlobalWafers Japan

**Japan Chapter of Traceability
Global Technical Committee**
C: Yoichi Iga – Self
C: Hirokazu Tsunobuchi – GENETEC
Corporation

Special Groups
Reporting to the
JRSC

**Standardization Process
Improvement (SPI) TF**
L: Supika Mashiro – Tokyo
Electron Limited

**JRSC Member at Large
(MAL)**
C: Shoji Komatsu – Acteon
NEXT

SEMI North America (NA) RSC Organization

NA Locale

NA Chapter of 3D Packaging & Integration Global Technical Committee C: Bill Kerr – Evergreen Enhancement C: Chris Moore – Consultant C: John Ciraldo – WD Advanced Material	NA Chapter of Flexible Hybrid Electronics Global Technical Committee C: Randall Parker – Disco Hi-Tec America C: Ahmed Busnaina – Northeastern University	NA Chapter of MEMS/NEMS Global Technical Committee C: Michelle Bourke – Lam Research C: Steve Martell – Consultant	NA Chapter of Physical Interfaces & Carriers Global Technical Committee C: Matt Fuller – Entegris C: Melvin Jung – Intel
NA Chapter of Automated Test Equipment Global Technical Committee C: Mark Roos – Roos Instruments C: Stacy Ajouri – Self	NA Chapter of Gases Global Technical Committee C: Mohamed Saleem – ITW	NA Chapter of Metrics Global Technical Committee C: David Bouldin – Fab Consulting C: Mark Frankfurth – Cymer C: Vladimir Kraz – BestESD	NA Chapter of Silicon Wafer Global Technical Committee C: Dinesh Gupta – STA C: Noel Poduje – SMS
NA Chapter of Compound Semiconductor Materials Global Technical Committee C: Russ Kremer – Consultant C: James Oliver – Northrop Grumman	NA Chapter of HB-LED Global Technical Committee C: Chris Moore – Consultant C: Andrew Kim – InnovationforX C: Mike Feng – Silian	NA Chapter of Microlithography Global Technical Committee C: Bryan Barnes – NIST	NA Chapter of Traceability Global Technical Committee C: Yaw Obeng – NIST C: David Huntley – PDF Solutions
NA Chapter of Environmental, Health & Safety Global Technical Committee C: Chris Evanston – Salus Engineering C: Sean Larsen – KLA	NA Chapter of Information & Control Global Technical Committee C: Brian Rubow – Cimetrix C: James Moyne – AMAT/ University of Michigan C: Albert Fuchigami – PEER Group	NA Chapter of Photovoltaic Global Technical Committee C: James Moyne – AMAT/University of Michigan	NA RSC Technical Architect Board C: James Moyne – AMAT/ University of Michigan C: Yaw Obeng – NIST
NA Chapter of Facilities Global Technical Committee C: Michael Potts – Arcadis DPS Group	NA Chapter of Liquid Chemicals Global Technical Committee C: Don Hadder – Intel C: Laura Ledenbach – Evonik C: David Kandiyeli – Kinetics (KESG) C: Per Nelson – Dakin America	NA Chapter of PV Materials Global Technical Committee C: Hugh Gotts – Air Liquide	

SEMI North America RSC Organization China Locale

**China Chapter of Compound
Semiconductor Materials
Global Technical Committee**

C: Jiangbo Wang – HC SEMITEK
C: Guoyou Liu – CRRC TIMES

**China Chapter of Photovoltaic
Global Technical Committee**

C: Dengyuan SONG – DASOLAR

**China Chapter of HB-LED
Global Technical Committee**

C: Jiangbo Wang – HC SEMITEK

**China Chapter of PV Materials
Global Technical Committee**

C: Dengyuan SONG – DASOLAR

**China Chapter of Information & Control
Global Technical Committee**

C: Xianfeng DING — ONEWO
C: Lingzhi Lv — FA Software
C: Clare Liu — KXWARE

ISC China Member

Jiangbo Wang – HC SEMITEK

SEMI North America RSC Organization Korea Locale

**Korea Chapter of
Environmental Health & Safety
Global Technical Committee**
C: Bruce Lim – Safe World Engineering
C: Dae Yong Roh – Samsung Electronics
C: Keun yong Park – SZU Korea
C: Hyuk Hwa Kwon – SK hynix

**Korea Chapter of FPD Metrology
Global Technical Committee**
C: Jaehong Kim – LG Display
C: Yongwoo Yi – Samsung Display

ISC Korea Member
Chul Hong Ahn – SK hynix

**Korea Chapter of Facilities
Global Technical Committee**
C: John Oh – SGS Korea
C: Kyung Man Kang – ICR

**Korea Chapter of Information & Control
Global Technical Committee**
C: Hyungsu Kim – Doople
C: Chul Hong Ahn – SK hynix
C: Gun Woo Lee – Lam Research

SEMI North America RSC Organization Taiwan Locale

**Taiwan Chapter of
3D Packaging & Integration
Global Technical Committee**
C: Wendy Chen – King Yuan Electronics
C: Jerry Wang – ITRI
C: Roger Hwang – ASE

**Taiwan Chapter of FPD Metrology
Global Technical Committee**
C: Jia-Ming Liu – TSOMDA
C: Jen-Chieh Wang – OmniMeasure
C: Yu-Ping Lan – ITRI

**Taiwan Chapter of Information & Control
Global Technical Committee**
C: J. S. Shiau – TSMC

**Taiwan Chapter of Automation Technology
Global Technical Committee**
C: Jen-Hui Tsai – ITRI
C: Jui-Ming Hua – MIRDC

**Taiwan Chapter of
Flexible Hybrid Electronics
Global Technical Committee**
C: Y.E. Yeh – ASE

**Taiwan Chapter of Photovoltaic
Global Technical Committee**
C: T.C. Wu – CMS/ITRI
C: Ray Sung – UL Taiwan
C: C.C. Lin – PV Guider

**Taiwan Chapter of
Environmental Health & Safety
Global Technical Committee**
C: C.C. Huang – SAHTECH
C: Jean Yang – Innolux

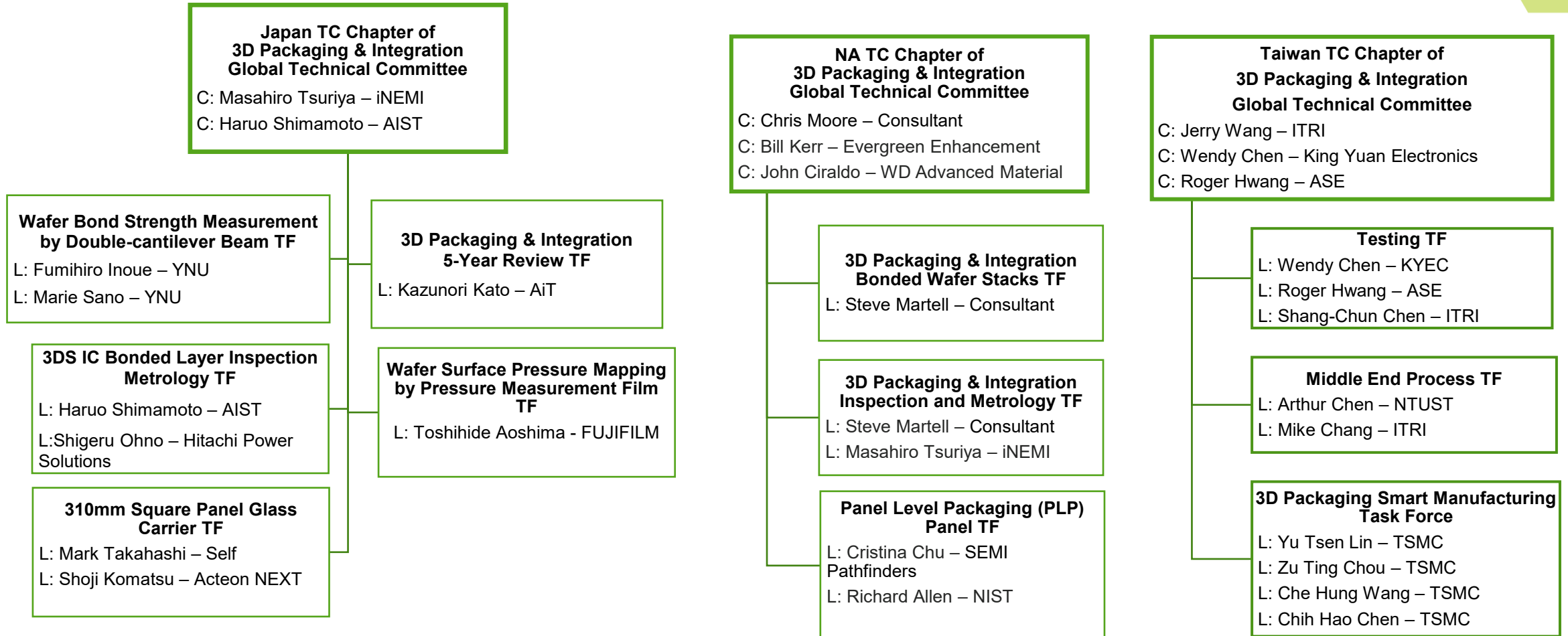
ISC Taiwan Member
Jen-Chieh Wang – OmniMeasure

Organization of Each TC Chapter

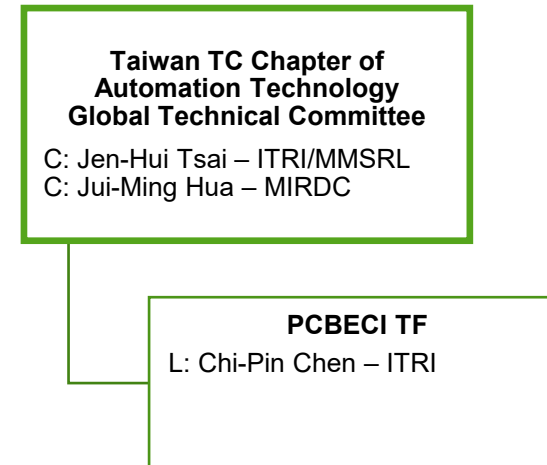
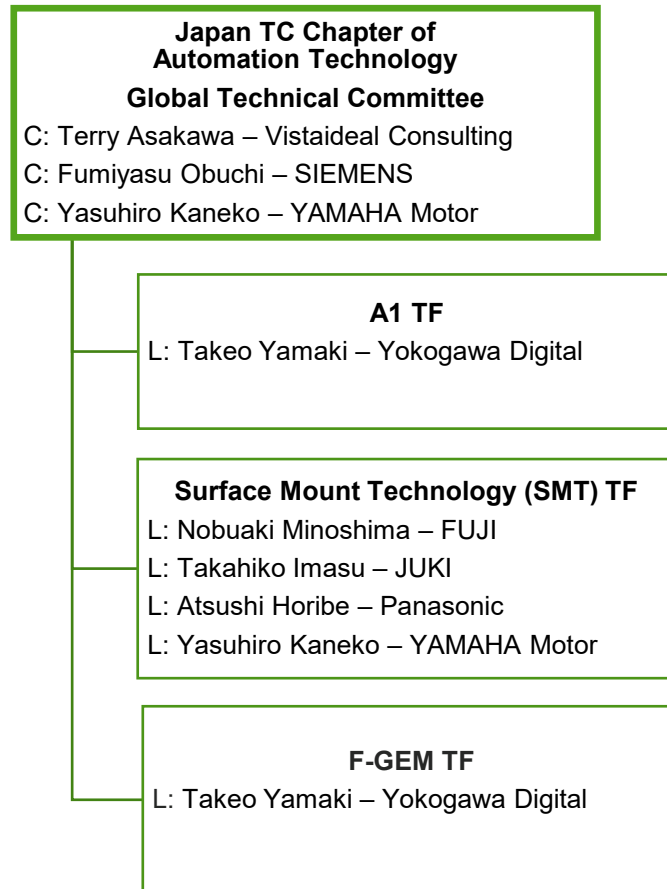
TF = Task Force

WG = Working Group

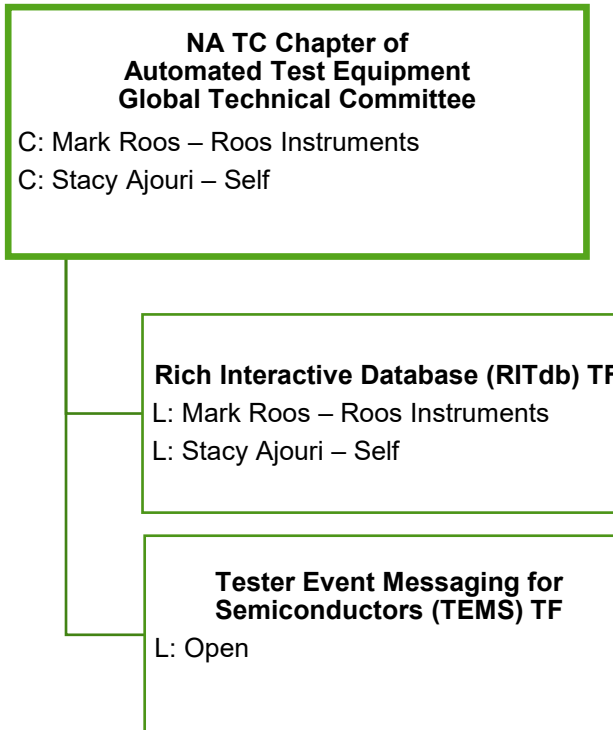
3D Packaging & Integration (3DP&I) Global Technical Committee



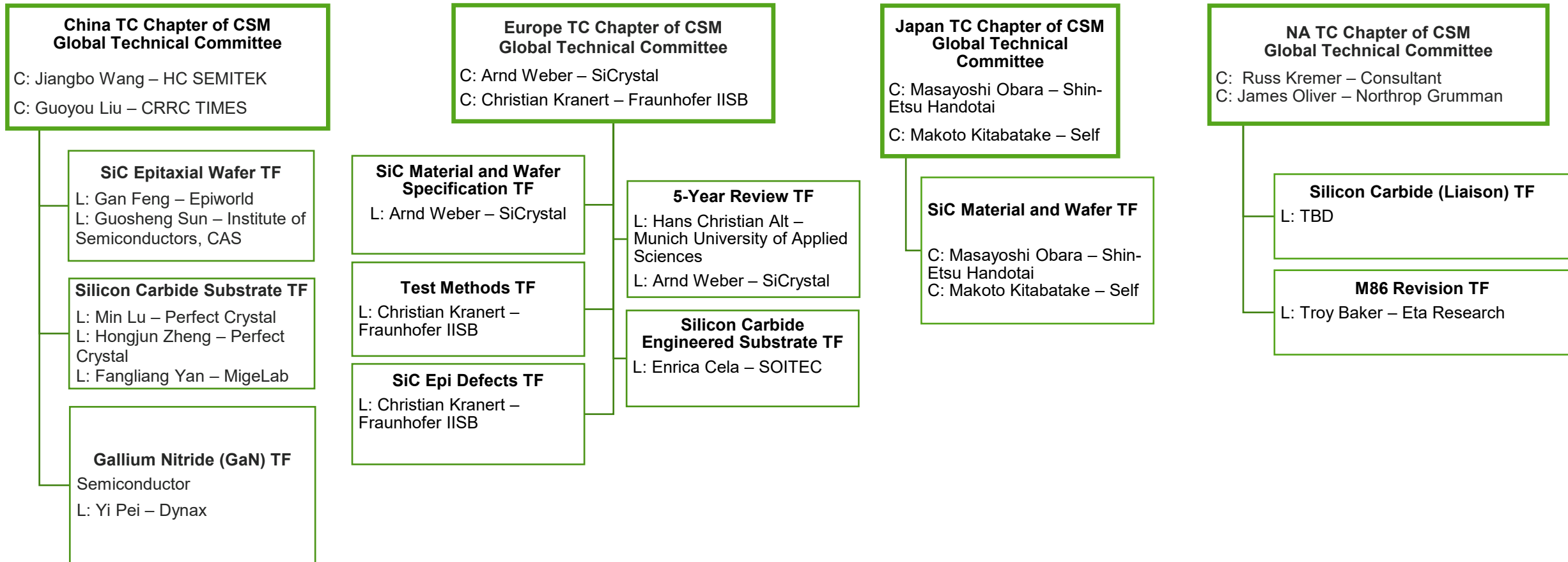
Automation Technology (AT) Global Technical Committee



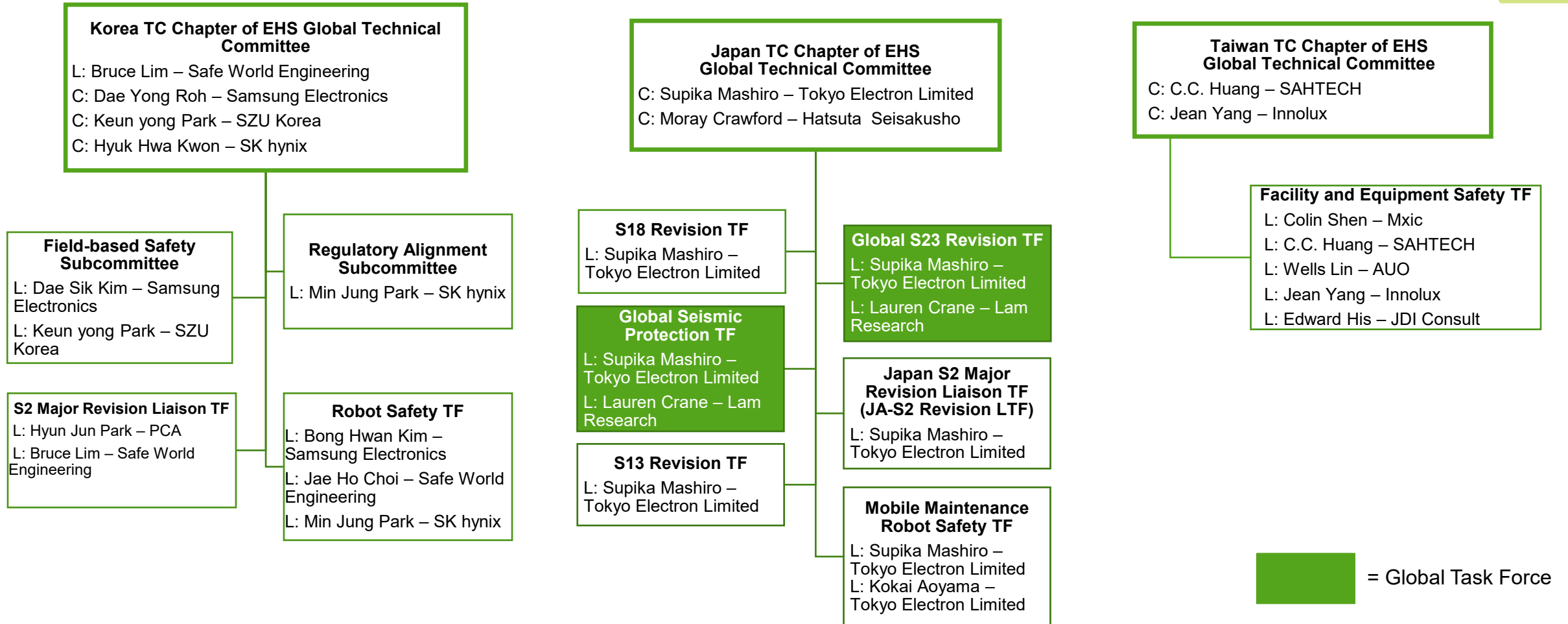
Automated Test Equipment (ATE) Global Technical Committee



Compound Semiconductor Materials (CSM) Global Technical Committee

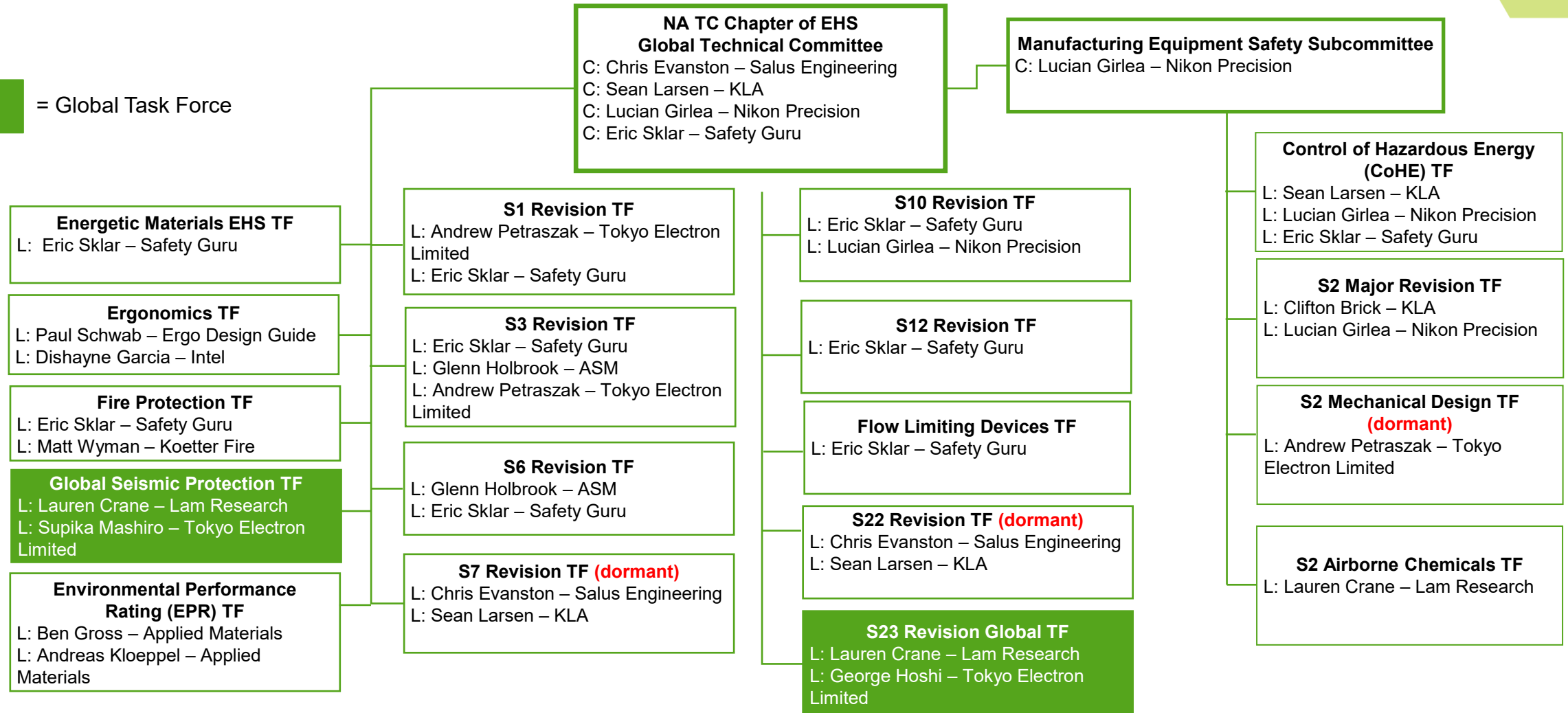


Environmental, Health & Safety (EH&S) Global Technical Committee [1/2]



Environmental, Health & Safety (EH&S) Global Technical Committee [2/2]

 = Global Task Force



Facilities Global Technical Committee

**Japan TC Chapter of Facilities
Global Technical Committee**
 C: Hiromichi Enami – i ZOOM
 C: Isao Suzuki – Consultant
 C: Masafumi Kitano – Fujikin

F1 Revision TF
 L: Masafumi Kitano – Fujikin
 L: Kazuhiko Takamisawa – NISSAN
 TANAKA

5-Year Review TF
 L: Masafumi Kitano – Fujikin

E137 Revision TF
 L: Haruna Hayashi – Tokyo Electron

**NA TC Chapter of Facilities
Global Technical Committee**
 C: Michael Potts – Arcadis DPS Group

F51 Revision TF
 L: Keith Zhao – ASNA
 L: Franics Vo – EKK Eagle
 America Inc.

**Manufacturing Equipment
Installation TF**
 L: Michael Potts – Arcadis DPS
 Group

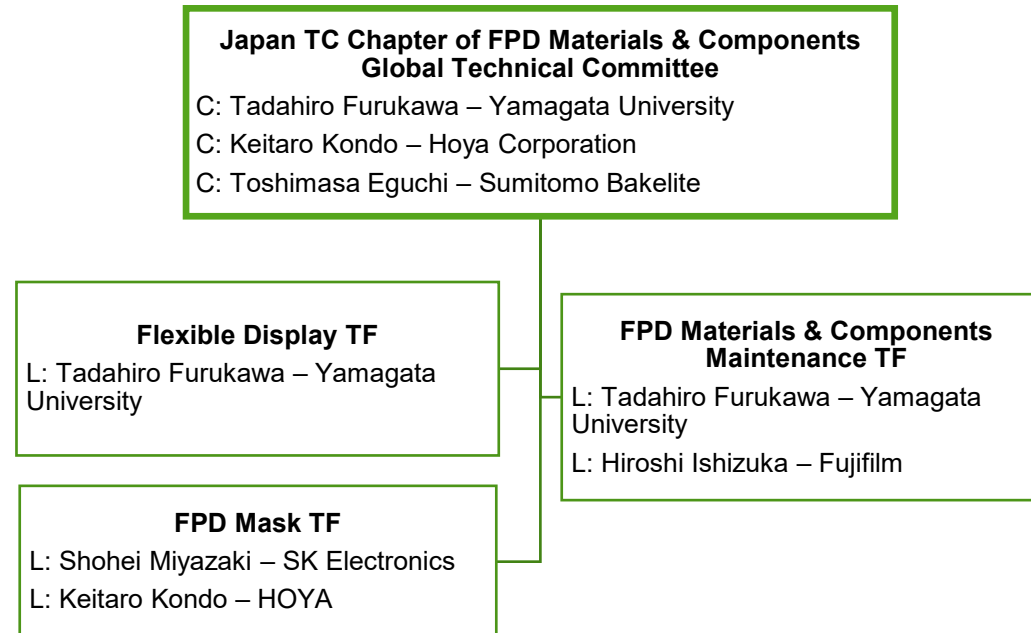
Power Grid Harmonics TF
 L: Open

Voltage Sag Immunity TF
 L: Mark Stephens – EPRI

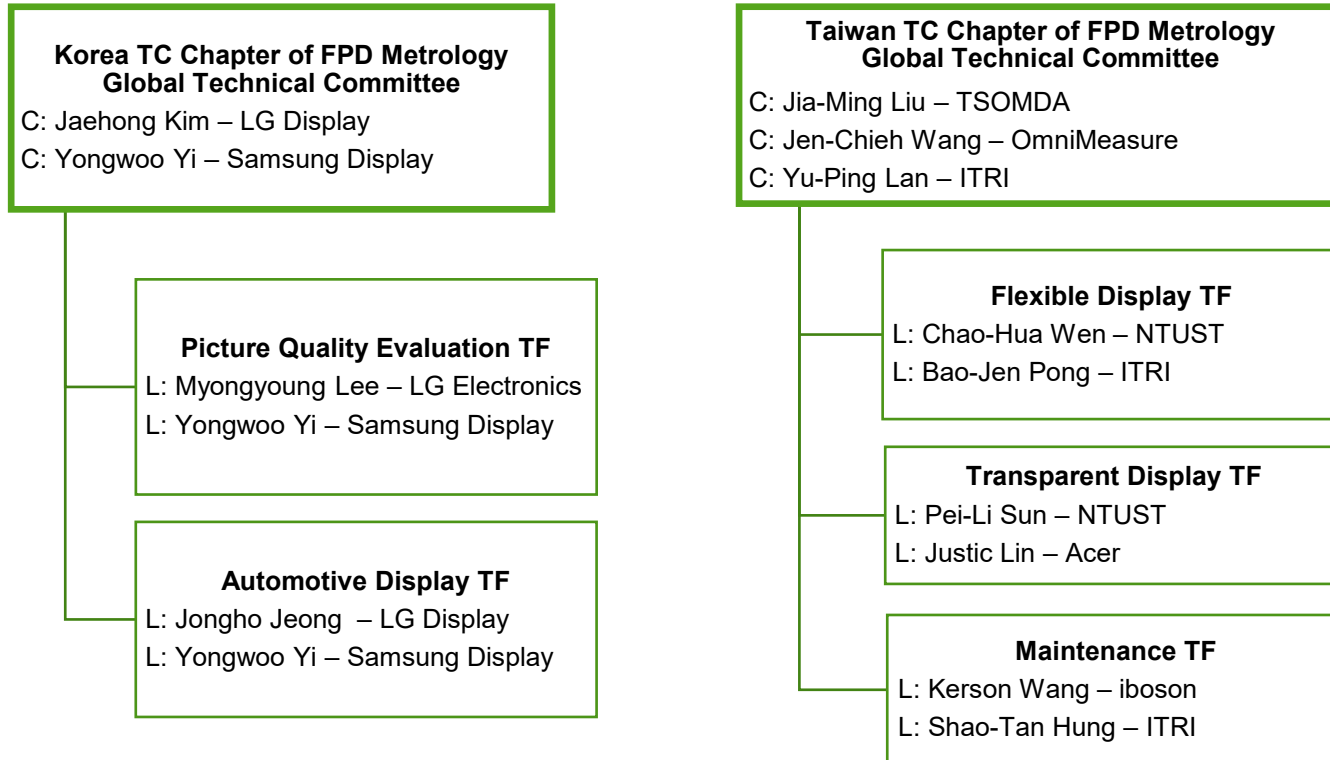
**Korea TC Chapter of Facilities
Global Technical Committee**
 C: John Oh – SGS Korea
 C: L: Kyung Man Kang – ICR

Voltage Sag Immunity TF
 L: Hohun Kang – Woori
 Engineering
 L: Jeong-Kyu Han – JAESHIN
 INFORMATION

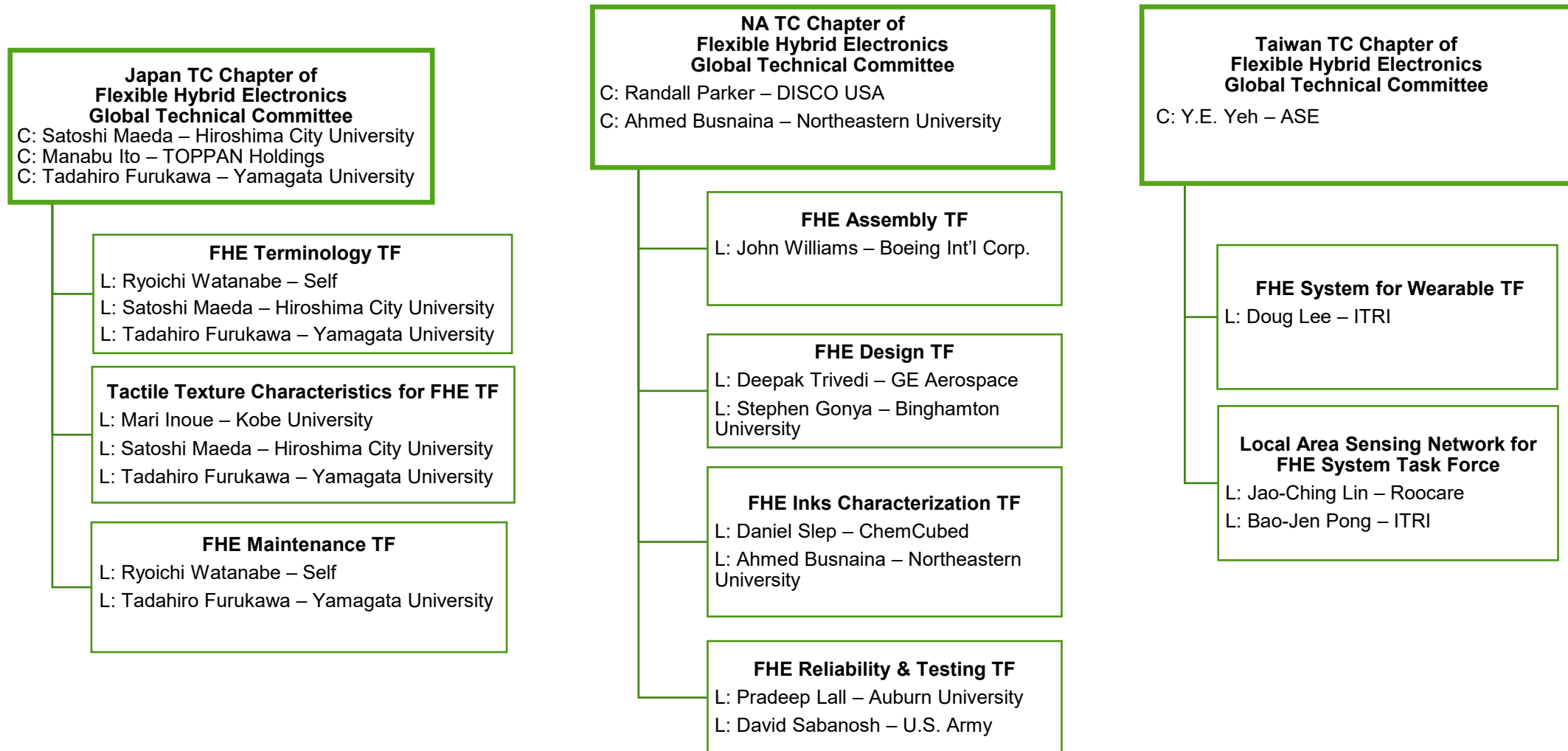
Flat Panel Display (FPD) - Materials & Components Global Technical Committee



FPD Metrology Global Technical Committee



Flexible Hybrid Electronics (FHE) Global Technical Committee



Gases Global Technical Committee

**Europe TC Chapter of Gases
Global Technical Committee**
C: Jochen Ruth – Pall Corporation

**Japan Chapter of Gases
Global Technical Committee**
C: Hiromichi Enami – i ZOOM
C: Isao Suzuki – Consultant
C: Masafumi Kitano – Fujikin

Five-Year Review TF
L: Masafumi Kitano – Fujikin

**NA TC Chapter of Gases
Global Technical Committee**
C: Mohamed Saleem – ITW

Filters & Purifiers TF
L: Mohamed Saleem – ITW
L: Yanli Chen – Applied Materials

Heater Jacket TF
L: David Colquhoun – Analog
Assocaites

Mass Flow Controller TF
L: Mohamed Saleem – ITW
L: Kevin Findleton – Ichor Systems

Gases Specification TF
L: Mohamed Saleem – ITW
L: Thomas Fritz – WIKA Corporation

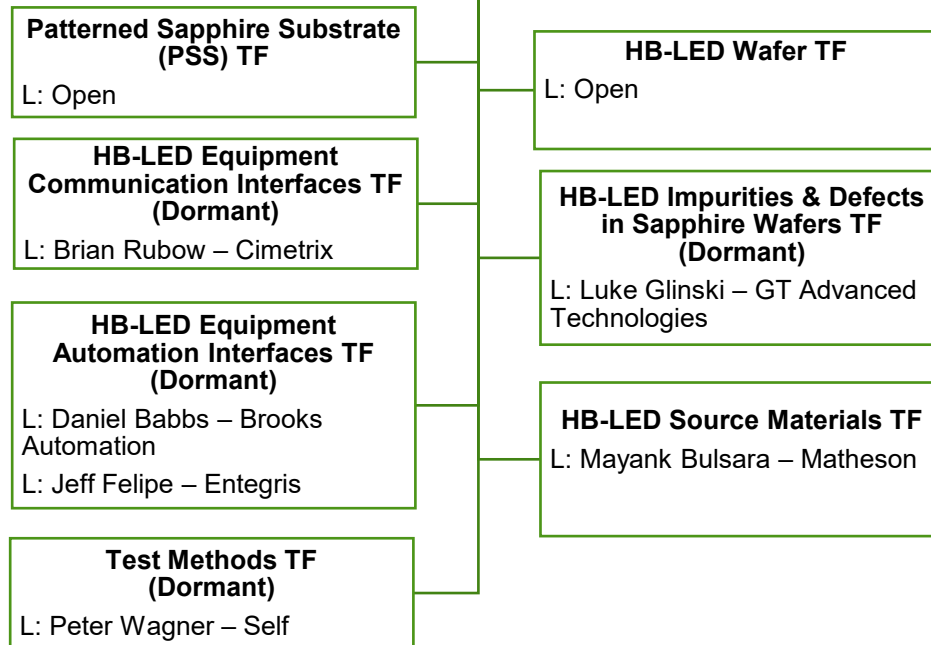
**Materials of Construction of Gas
Delivery Systems TF**
L: Matt Milburn – UCT
L: Max van den Berg – Festo

**Pressure Measurement TF
(Dormant)**
L: Yanli Chen – Applied Materials
L: Jeff Christian – WIKA Corporation

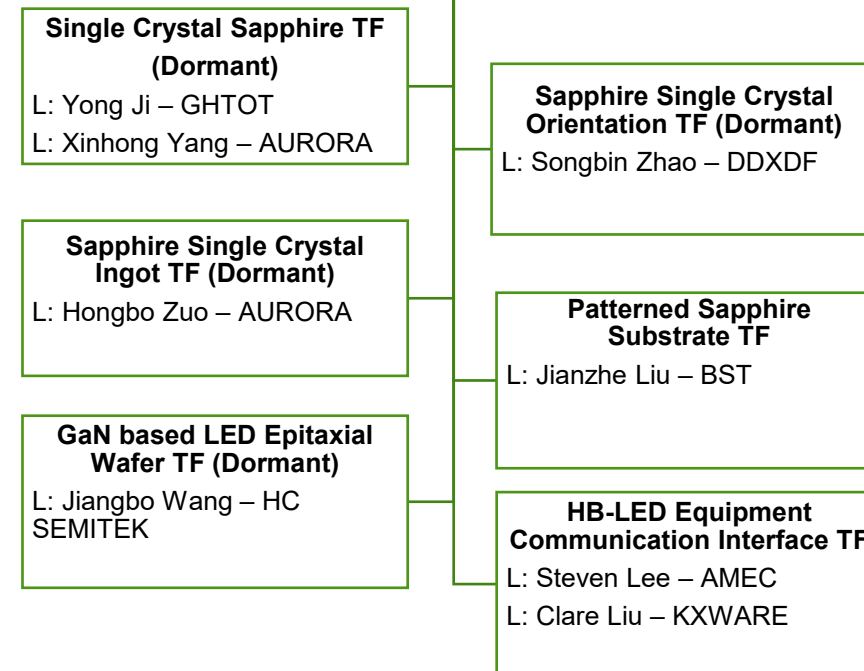
**Surface Mount Sandwich
Component Dimensions TF
(Dormant)**
L: Matt Milburn – UCT

HB-LED Global Technical Committee

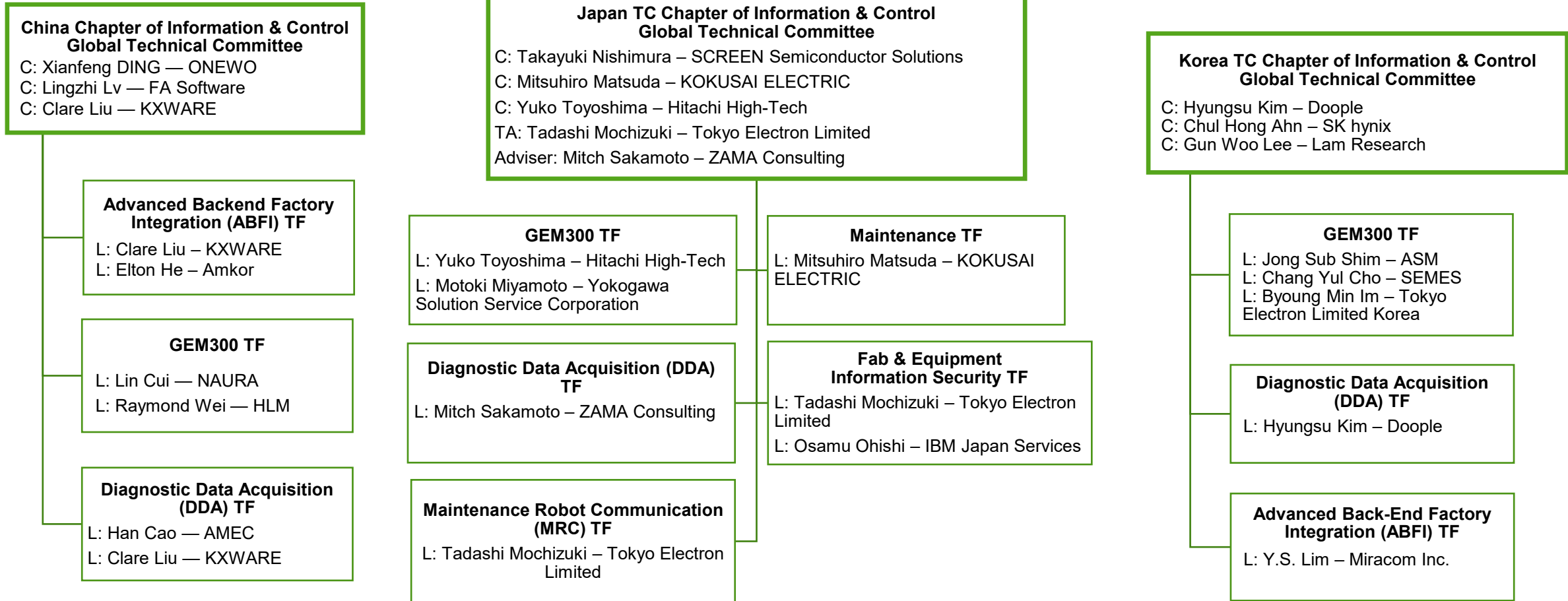
**NA TC Chapter of HB-LED
Global Technical Committee**
 C: Andrew Kim – InnovationforX
 C: Mike Feng – Silian
 C: Chris Moore – Consultant



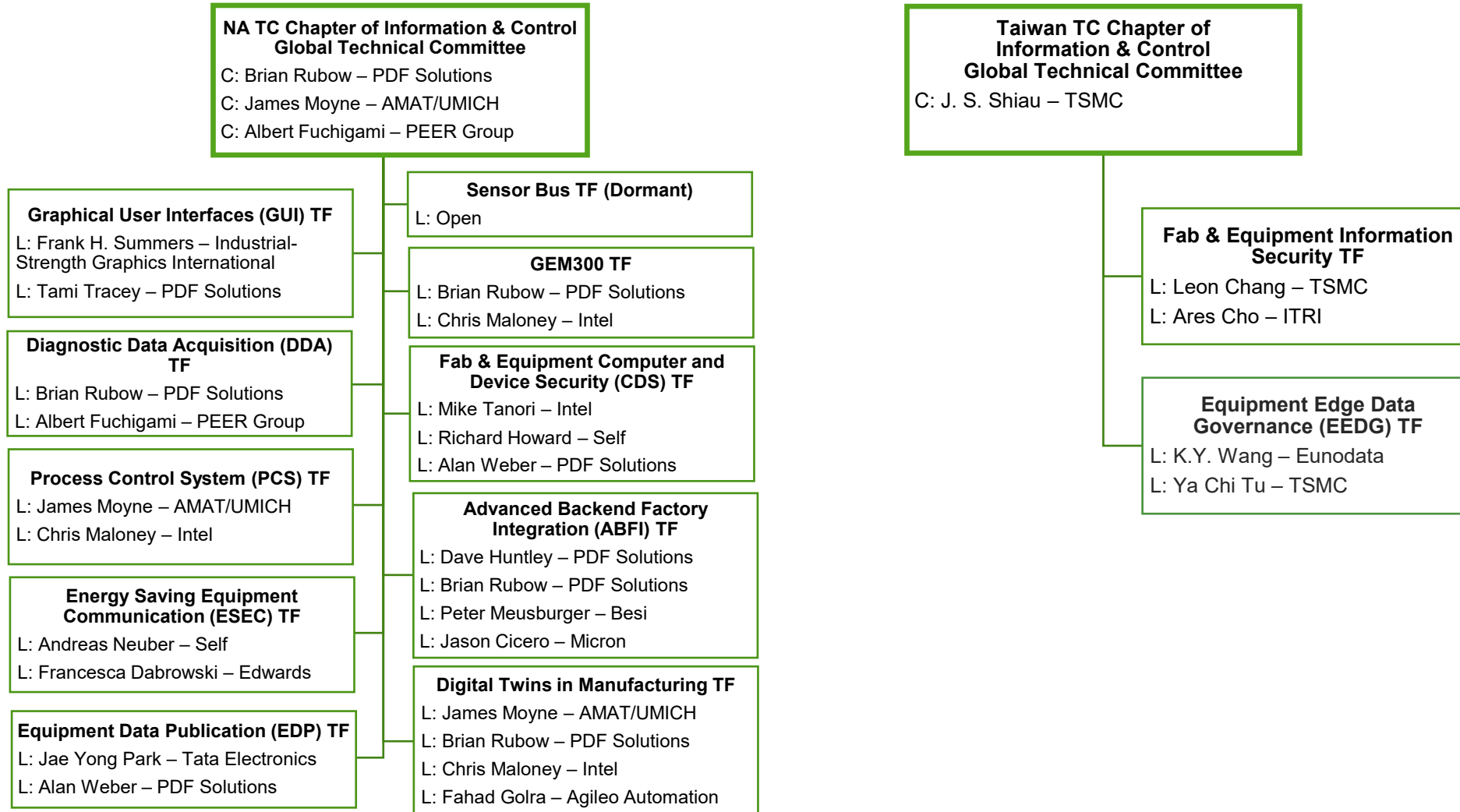
**China TC Chapter of HB-LED
Global Technical Committee**
 C: Jiangbo Wang – HC SEMITEK



Information & Control (I&C) Global Technical Committee [1/2]



Information & Control (I&C) Global Technical Committee [2/2]



Liquid Chemicals Global Technical Committee

**Europe TC Chapter of
Liquid Chemicals
Global Technical Committee**
C: Jochen Ruth – Pall Corporation

**Japan TC Chapter of Liquid Chemicals
Global Technical Committee**
C: Yoshiyuki Fujitani – SCREEN
Semiconductor Solutions
C: Takuya Nagafuchi – Nihon Entegris

**NA TC Chapter of Liquid Chemicals
Global Technical Committee**
C: Don Hadder – Intel
C: Laura Ledenbach – Evonik
C: David Kandiyeli – Kinetics (KESG)
C: Per Nelson – Daikin America

Liquid Filter TF
L: Takuya Nagafuchi – Nihon Entegris
L: Hisashi Nakagawa – Pall

Liquid-Borne Particle Counter TF
L: Masaki Shimmura – RION
L: Mitsuyoshi Takeshita – Particle
Measuring Systems

**Trace Metal Analysis for High Pure IPA
TF**
L: Takuya Nagafuchi – Nihon Entegris

Valve & Fitting TF
L: Kimihito Sasao – Advance Electric Co.
L: Masaji Inoue – PILLAR Corporation
L: Hiroto Yasue – CKD Corporation

**Chemical Analytical Methods
(CAM) TF**
L: Don Hadder – Intel
L: David Kandiyeli – KESG

**High Purity Polymer Materials
& Components TF**
L: Bob McIntosh – GF Piping
L: Per Nelson – Daikin America

Water Management TF
L: Paul Kerr – Sargent & Lundy
L: Slava Libman – FTD solutions

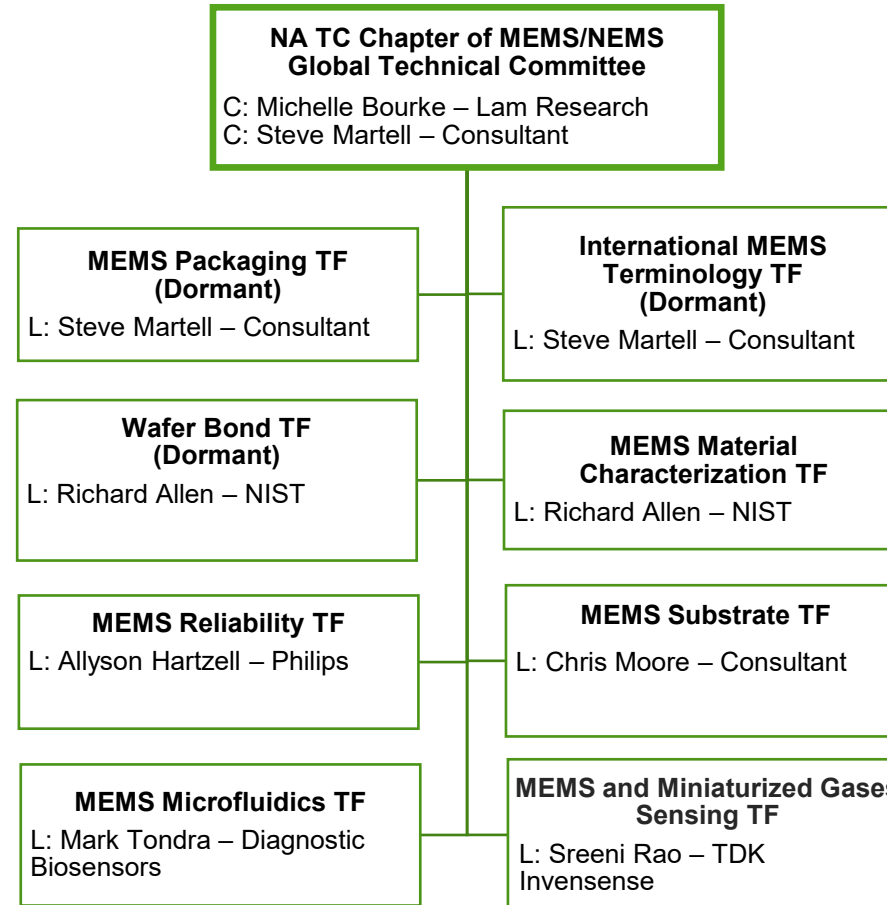
**Statistical Methods TF
(Dormant)**
L: Thomas Bzik – Self

**High Purity Liquid Assemblies
& Systems TF**
L: David Kandiyeli – KESG

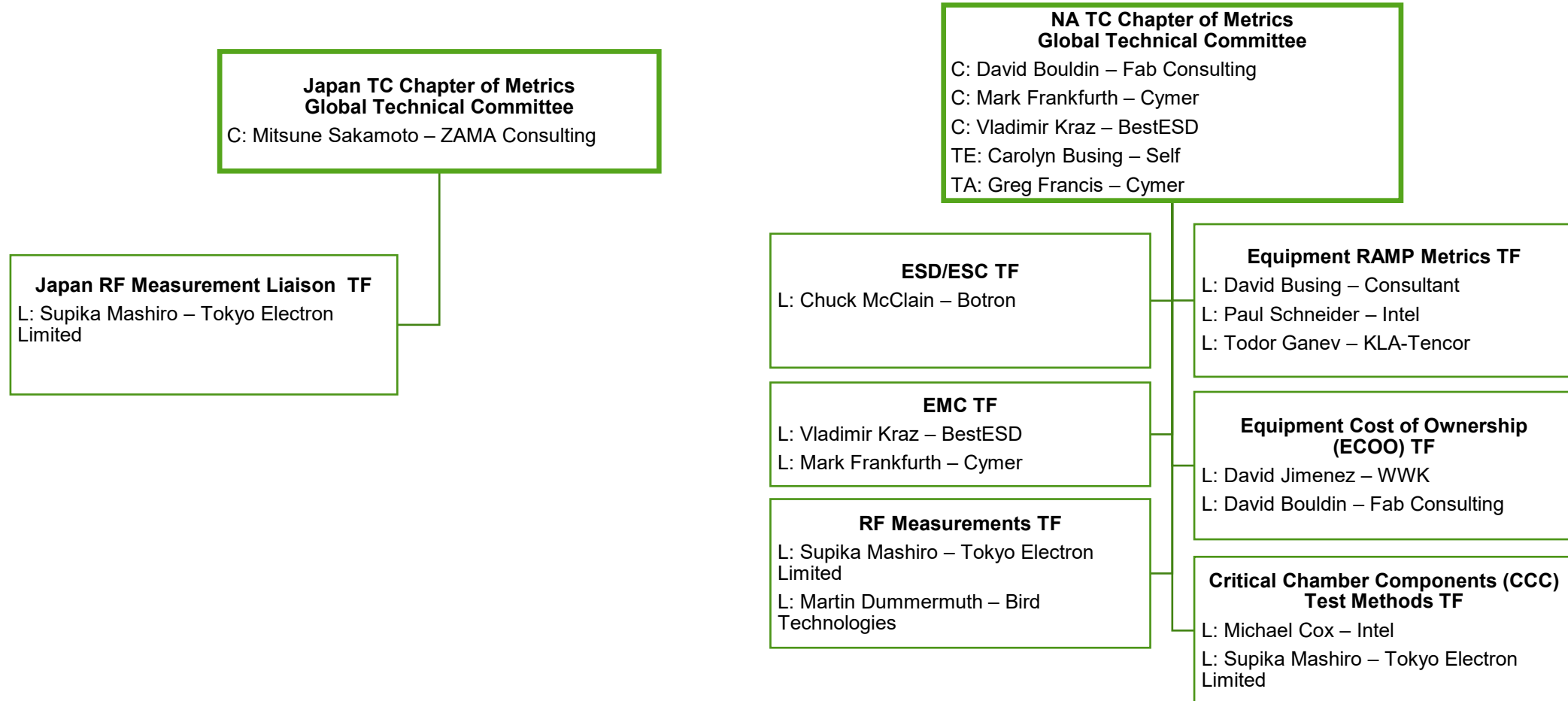
Ultra Pure Water (UPW) TF
L: Lindsey Sullivan – FTD
solutions
L: Gary van Schooneveld – CT
Associates
L: Bob McIntosh – GF Piping

**Chemical Mechanical
Planarization Consumables
(CMP-C) TF**
L: Amanda David – Intel
L: Alex Tregub – Alex Technical
Consulting and Publishing

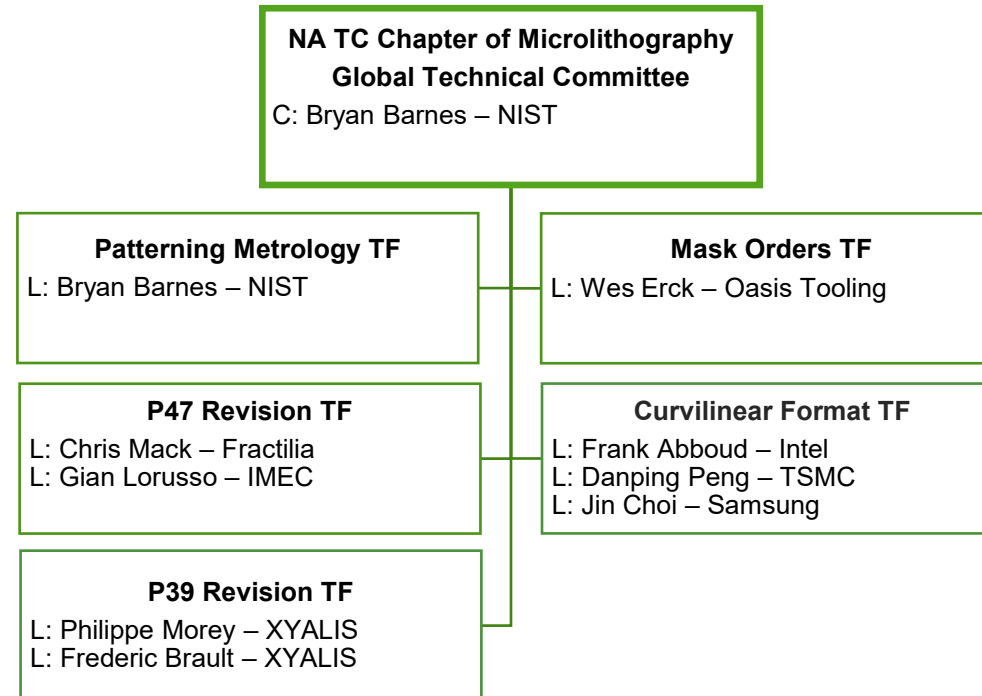
MEMS/NEMS Global Technical Committee



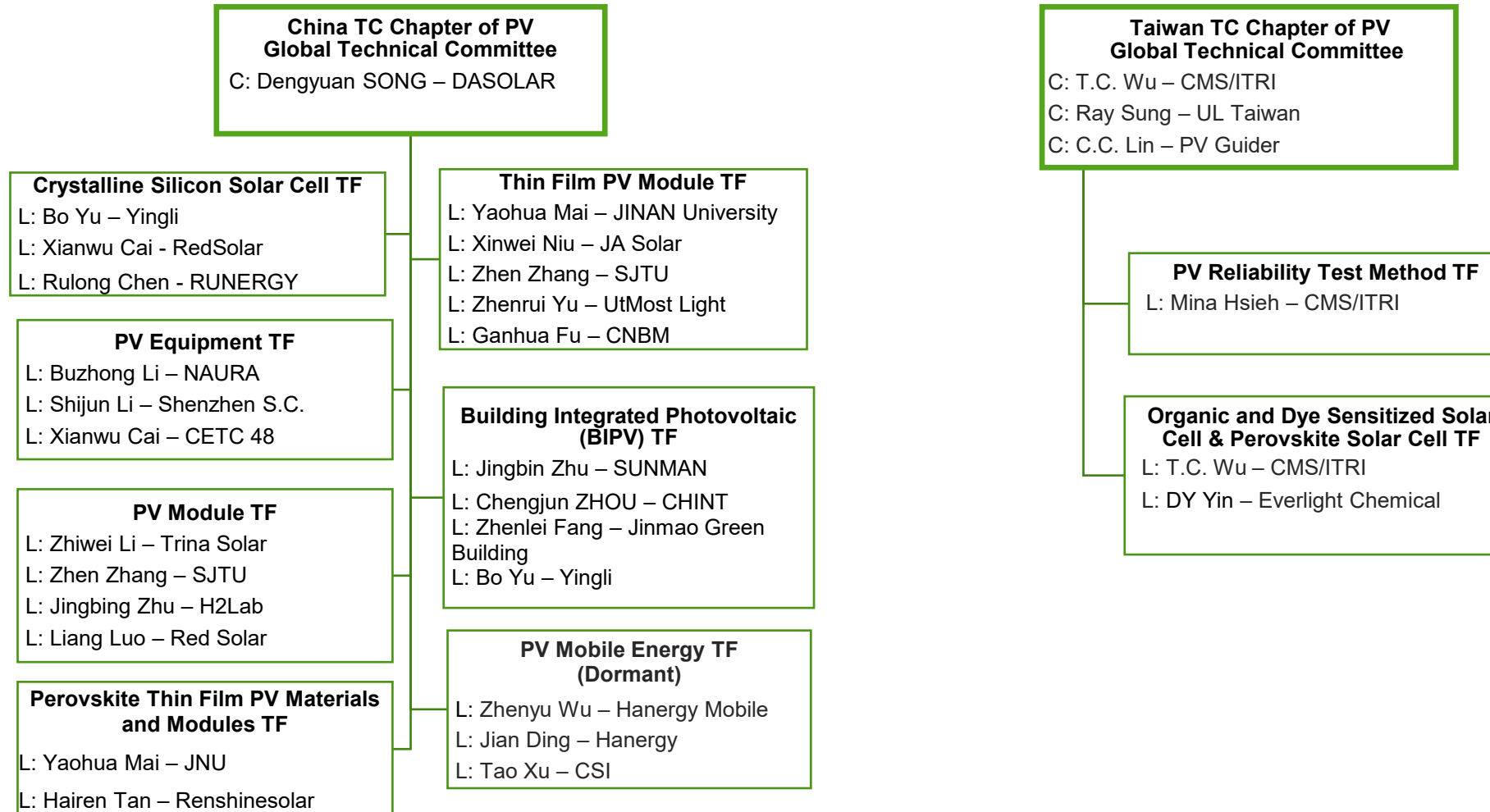
Metrics Global Technical Committee



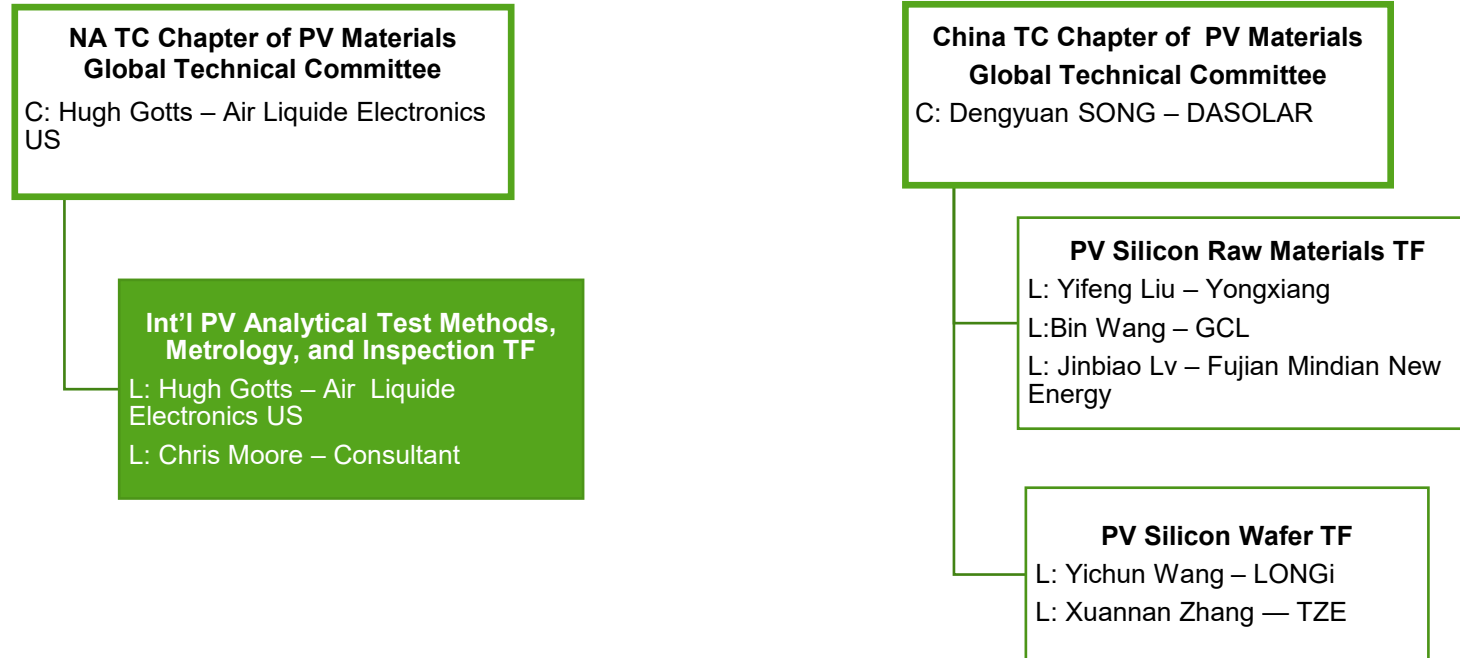
Micropatterning / Microlithography Global Technical Committee



Photovoltaic (PV) Global Technical Committee

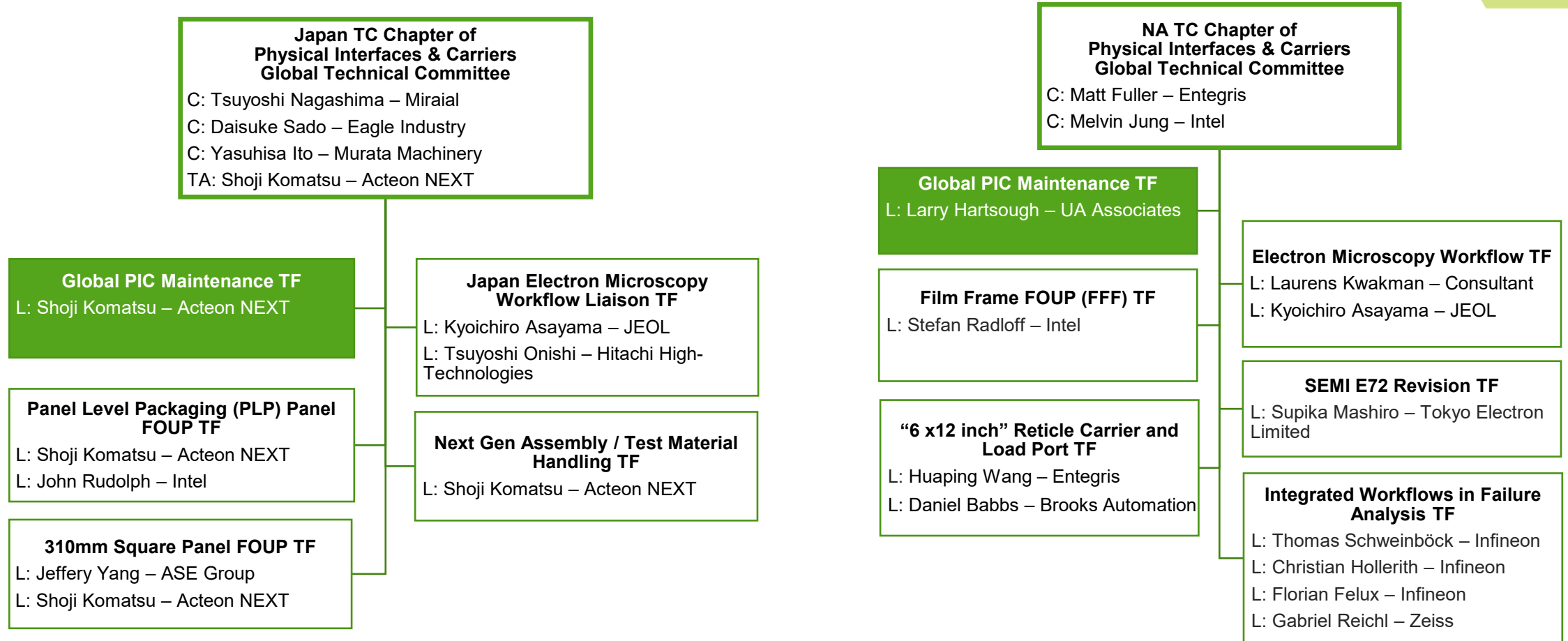


PV Materials Global Technical Committee



 = Global Task Force

Physical Interfaces & Carriers (PI&C) Global Technical Committee



= Global Task Force

Silicon Wafer Global Technical Committee [1/2]

**Europe TC Chapter of Silicon Wafer
Global Technical Committee**
 C: Werner Bergholz – Jacobs University of Bremen
 C: Fritz Passek – Siltronic
 C: Frank Riedel – Siltronic

**International Advanced Surface
Inspection TF**
 L: Judith Wittmann – Siltronic

International Terminology TF
 L: TBD

International Polished Wafers TF
 L: Cristina Sanna - GlobalWafers

**International Advanced Wafer
Geometry TF**
 L: Fritz Passek – Siltronic
 L: Frank Riedel – Siltronic

International Test Methods TF
 L: Thomas Hager – Siltronic

**NA TC Chapter of Silicon Wafer
Global Technical Committee**
 C: Dinesh Gupta – STA
 C: Noel Poduje – SMS

International Annealed Wafers TF
 L: Dinesh Gupta – STA

International Epitaxial Wafers TF
 L: Dinesh Gupta – STA

International Polished Wafers TF
 L: Open


International SOI Wafers TF
 L: Gerd Pfeiffer – SOITEC

International Terminology TF
 L: Open

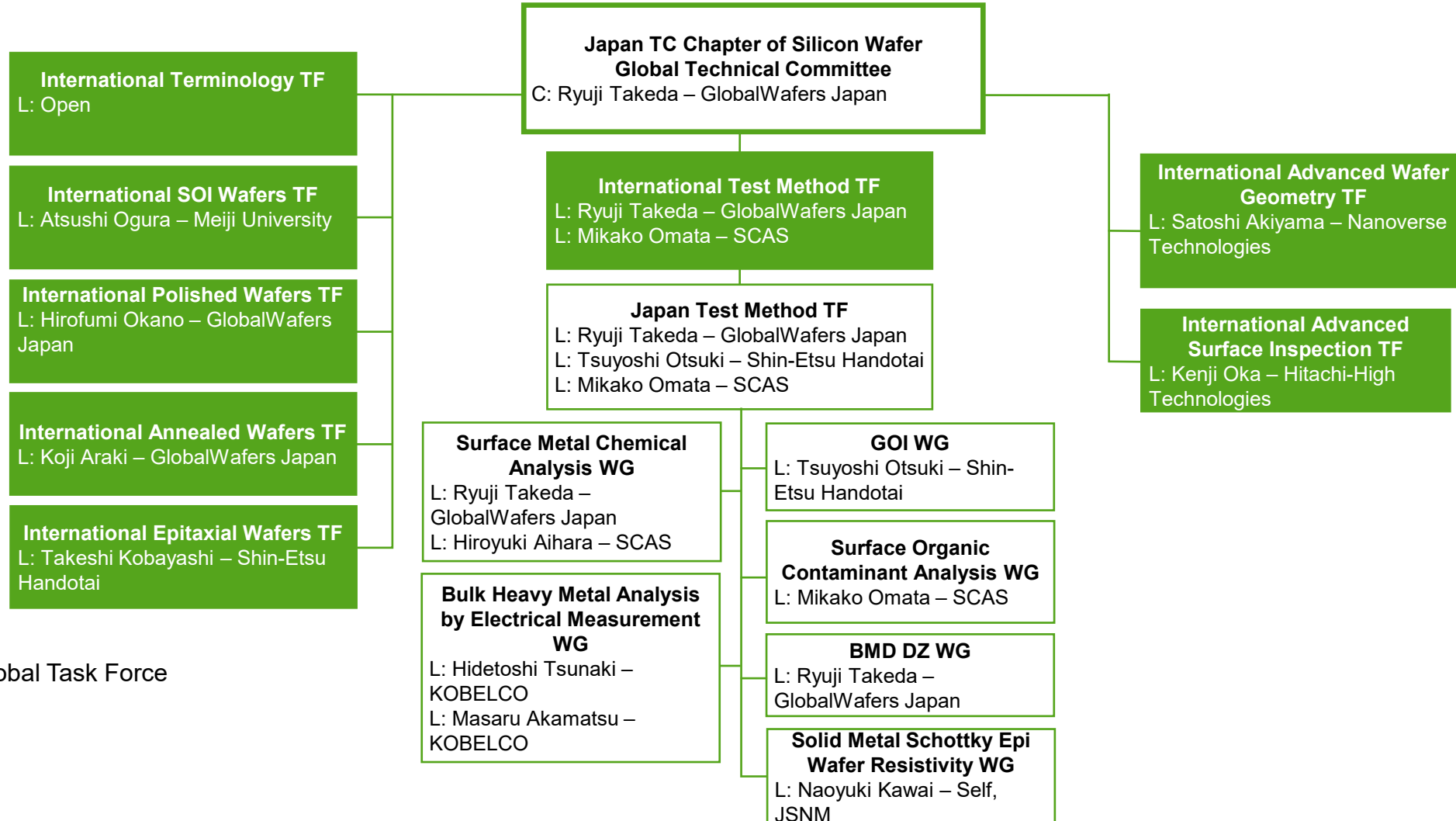
International Test Methods TF
 L: Dinesh Gupta – STA

**International Advanced Wafer
Geometry TF**
 L: Noel Poduje – SMS

**International Automated
Advance Surface Inspection TF**
 L: Kurt Haller – KLA

 = Global Task Force

Silicon Wafer Global Technical Committee [2/2]



= Global Task Force

Traceability Global Technical Committee

